

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7441132

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
FENG-CHENG HSU	07/16/2020
SHIN-PUU JENG	07/29/2020
SHUO-MAO CHEN	07/29/2020
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17813648
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ATTORNEY DOCKET NUMBER:	252056-1251
NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/
DATE SIGNED:	07/20/2022
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Feng-Cheng HSU, Shin-Puu JENG and Shuo-Mao CHEN
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as
described and set forth in the below identified application for United States Letters Patent:

Title: CHIP PACKAGE STRUCTURE WITH INTEGRATED DEVICE INTEGRATED
BENEATH THE SEMICONDUCTOR CHIP

Filed: 2020-07-07 Serial No. 16,922,132
Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu
Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous
of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters
Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and
valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have
sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said
Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to
the said invention and application and all future improvements thereon, and in and to any Letters
Patent which may hereafter be granted on the same in the United States, the said interest to be held
and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by
said Assignor had this Assignment and transfer not been made, to the full end and term of any
Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or
in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee,
but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or
applications, execute, verify, acknowledge and deliver all such further papers, including
applications for Letters Patent and for the reissue thereof, and instruments of assignment and
transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or
maintain Letters Patent for said invention and improvement, and to vest title thereto in said
Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)
indicated.

ASSIGNMENT

7/16/2020

Date

Feng-Cheng Hsu

Name: Feng-Cheng HSU

7/29/2020

Date

Shin-Puu Jeng

Name: Shin-Puu JENG

7/29/2020

Date

Shuo-Mao Chen

Name: Shuo-Mao CHEN